Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half-wave silicon gate-controlled devices are needed.

- Blocking Voltage to 800 Volts
- On–State Current Rating of 12 Amperes RMS at 80°C
- High Surge Current Capability 100 Amperes
- Rugged, Economical TO220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of IGT, VGT an IH Specified for Ease of Design
- High Immunity to dv/dt 100 V/µsec Minimum at 125°C
- Device Marking: Logo, Device Type, e.g., MCR12D, Date Code

Rating Symbol Value Unit Peak Repetitive Off–State Voltage⁽¹⁾ Volts VDRM. $(T_J = -40 \text{ to } 125^\circ \text{C}, \text{ Sine Wave},$ VRRM 50 to 60 Hz, Gate Open) 400 MCR12D MCR12M 600 800 MCR12N **On-State RMS Current** 12 А IT(RMS) (180° Conduction Angles; $T_C = 80^{\circ}C$) Peak Non-repetitive Surge Current А ITSM 100 (1/2 Cycle, Sine Wave 60 Hz, T_{.1} = 125°C) **Circuit Fusing Consideration** l²t A²sec 41 (t = 8.33 ms)Forward Peak Gate Power 5.0 Watts PGM (Pulse Width \leq 1.0 µs, T_C = 80°C) Forward Average Gate Power 0.5 Watts PG(AV) $(t = 8.3 \text{ ms}, T_C = 80^{\circ}C)$ Forward Peak Gate Current 2.0 А IGM (Pulse Width \leq 1.0 µs, T_C = 80°C) °C **Operating Junction Temperature Range** ТJ -40 to +125 -40 to °C Storage Temperature Range Tstg +150

(1) $V_{\mbox{DRM}}$ and $V_{\mbox{RRM}}$ for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

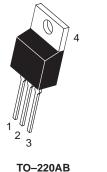


ON Semiconductor

http://onsemi.com

SCRs **12 AMPERES RMS** 400 thru 800 VOLTS





CASE 221A STYLE 3

PIN ASSIGNMENT				
1	Cathode			
2	Anode			
3	Gate			
4	Anode			

ORDERING INFORMATION

Device	Package	Shipping
MCR12D	TO220AB	50 Units/Rail
MCR12M	TO220AB	50 Units/Rail
MCR12N	TO220AB	50 Units/Rail

Preferred devices are recommended choices for future use and best overall value

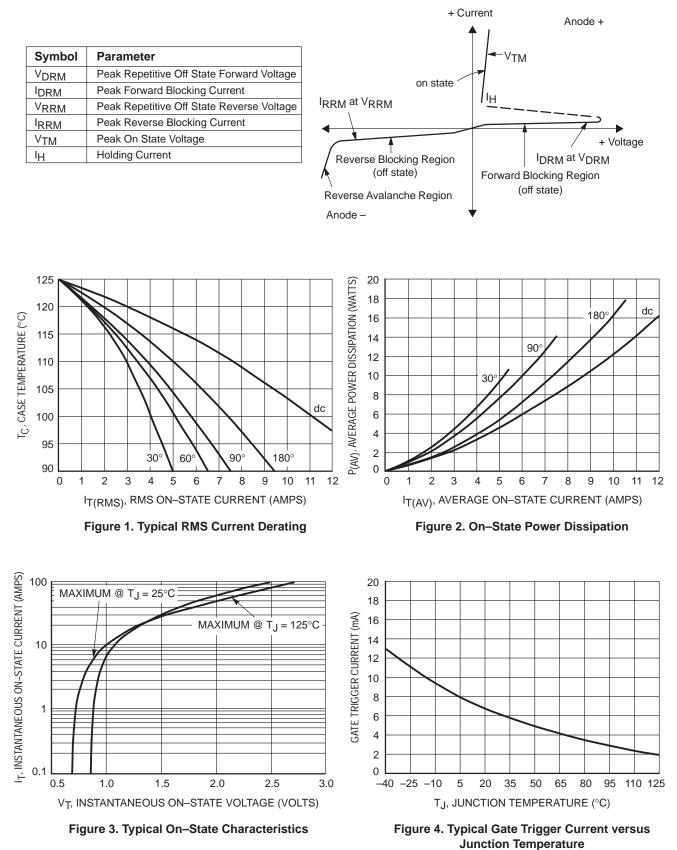
MAXIMUM RATINGS (T₁ = 25°C unless otherwise noted)

THERMAL CHARACTERISTICS

Characteristic			Symbol		Value	
Thermal Resistance — Junction to Case — Junction to Ambient			R _θ JC R _θ JA		2.2 62.5	
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds			т∟		260	
ELECTRICAL CHARACTERISTICS (T _J = 25° C unless otherwise n	oted)	-				
Characteristic	Symb	ol N	lin	Тур	Max	Unit
OFF CHARACTERISTICS	•					•
Peak Repetitive Forward or Reverse Blocking Current $(V_D = Rated V_{DRM} and V_{RRM}; Gate Open)$ $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$			_		0.01 2.0	mA
ON CHARACTERISTICS						
Peak Forward On–State Voltage* (I _{TM} = 24 A)	VTN	1 -	_	_	2.2	Volts
Gate Trigger Current (Continuous dc) (V_D = 12 V; R_L = 100 Ω)		. 2	.0	8.0	20	mA
Holding Current (V _D = 12 V, Gate Open, Initiating Current = 200 mA)		4	.0	20	40	mA
Latch Current (V _D = 12 V, I _G = 20 mA)		6	5.0	25	60	mA
Gate Trigger Voltage (Continuous dc) (V _D = 12 V; R _L =100 Ω)		r C	.5	0.65	1.0	Volts
DYNAMIC CHARACTERISTICS	•	•				
Critical Rate of Rise of Off–State Voltage (V_D = Rated V_{DRM} , Exponential Waveform, Gate Open, T _J = 125°C)		lt 1	00	250	_	V/µs
Repetitive Critical Rate of Rise of On–State Current IPK = 50 A, Pw = 40 μsec, diG/dt = 1 A/μsec, Igt = 50 mA		t -	_	-	50	A/μs

*Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%.

Voltage Current Characteristic of SCR



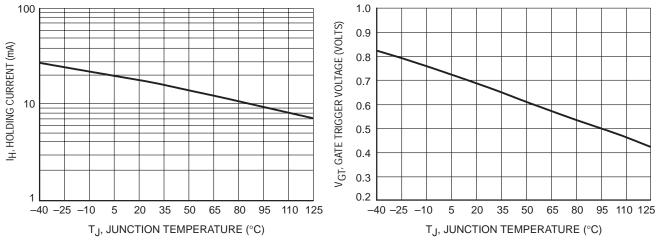


Figure 5. Typical Holding Current versus Junction Temperature

Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

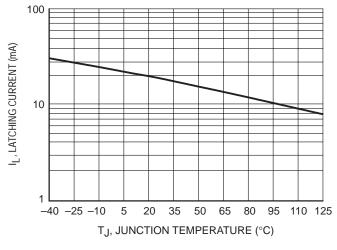
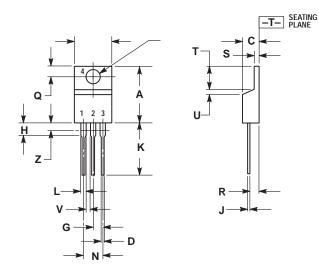


Figure 7. Typical Latching Current versus Junction Temperature

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 **ISSUE Z**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.018	0.025	0.46	0.64	
К	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
Ν	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Ζ		0.080		2.04	

STYLE 3: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE

Notes

Notes

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